QIMS2.E357716
Mounting Systems, Mounting Devices, Clamping Devices and Ground Lugs for Use with Photovoltaic Modules and Panels - Component

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DYNORAXX June 05, 2013 E357716
Suite 120
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Photovoltaic module bonding devices, Cat. No. Dynobond. (*Report Date: 2013-05-31*)

Conditions of Acceptability:

1. These devices have been evaluated using representative sections of anodized aluminum frames, over a range of thickness and minimum flange capture depth. Compatibility with any Listed PV module frame must be determined in the end-use application.
2. These devices have been evaluated for bonding up to a maximum over-current protection level of 20 Amps through the Bonding Path Resistance Test, which was conducted before and after the Temperature Cycling Test, Humidity Test and Bonding Conductor Test, as outlined in UL 2703. Acceptability for use with specific grounding systems must be determined in the end-use application.
3. The DynoBond clip is attached to the modules using spring force and a piercing function to penetrate the anodized coating of the flat bottom portion of Listed Module frames. Acceptance of this interconnection as a grounding path shall be determined in the end-use application.

Marking: Company name, catalog designation and the Recognized Component Mark on the device or on the smallest unit container in which the product is packaged.